HONANT

WiFi/Bluetooth Ceramic Chip Antenna

HCA2012B2450D08S

Description

The HCA2012B2450D08S chip antenna is designed for WiFi/Bluetooth applications. This chip antenna has excellent stability consistently provide high signal reception efficiency.

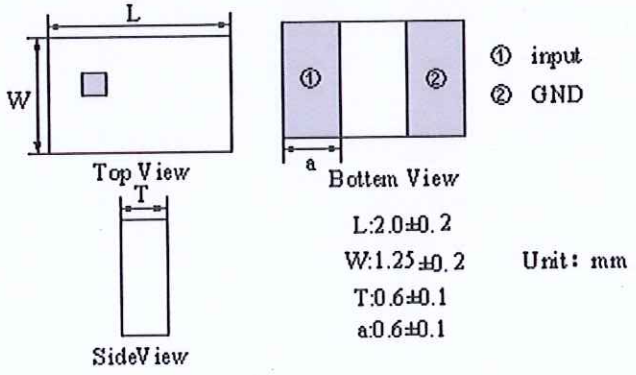
Features

- Dimensions 2.0 x 1.2 x 0.6 (mm)
- Stable and reliable in performances
- Low temperature coefficient of frequency
- Low profile , compact size
- RoHS compliance
- SMT processes compatible

Applications

- Bluetooth earphone systems
- Hand-held devices when WiFi /Bluetooth functions are needed, e.g., Smart phone.
- IEEE802.11 b/g/n
- ZigBee
- Wireless PCMCIA cards or USB dongle

Shape and Dimensions / Recommended Pattern



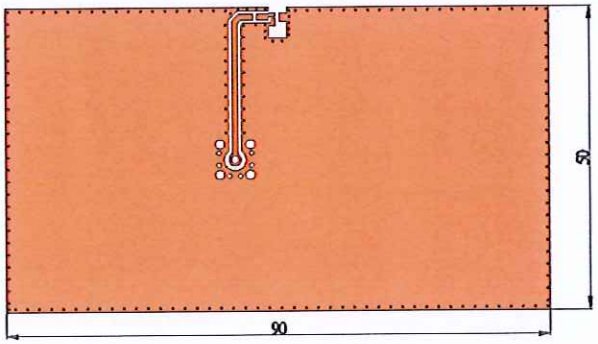
Electrical Specifications

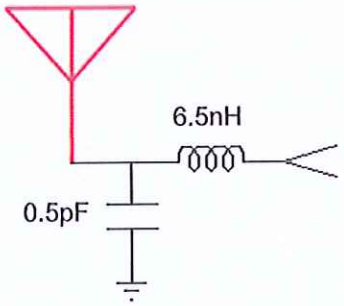
Electrical Table

Item	Specifications
Working Central Frequency (After matching)	2450 MHz
Band Width	65MHz typ.
Peak Gain	2.7 dBi
V.S.W.R (in BW)	≤2.0
Polarization	Linear
Azimuth Beam width	Omni-directional
Impedance	50 Ω

Matching Circuit

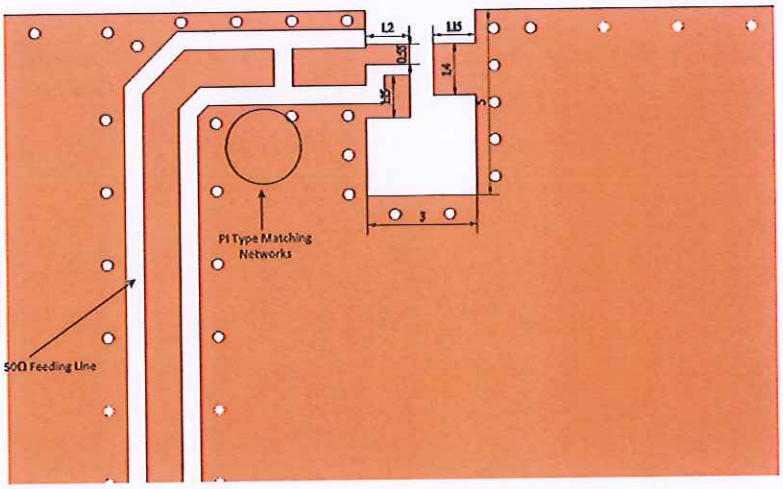
With the following recommended values of matching and tuning components, the center frequencies will be about 2450 MHZ at our standard 50x90 mm2 evaluation board . However, these are reference values, may need to be changed when the circuit boards or part vendors are different.



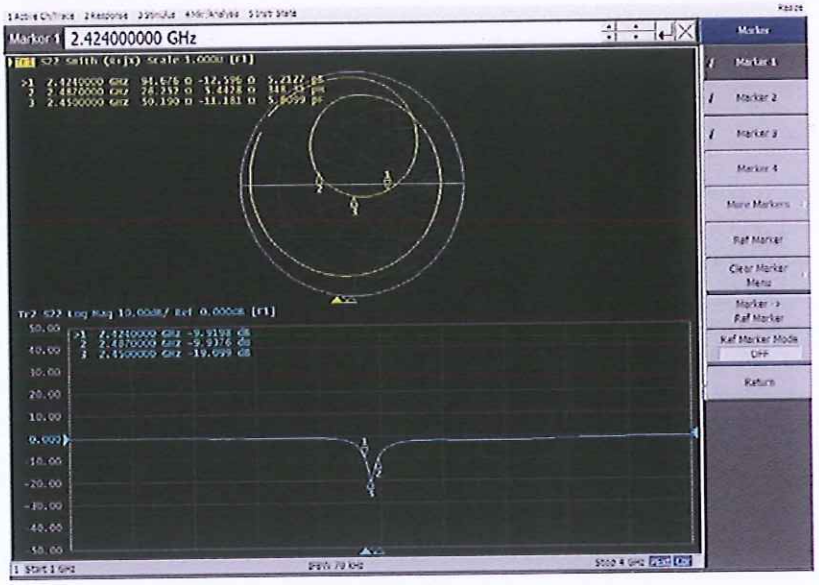


Dimensions and Recommended PC Board pattern

PCB Top View :

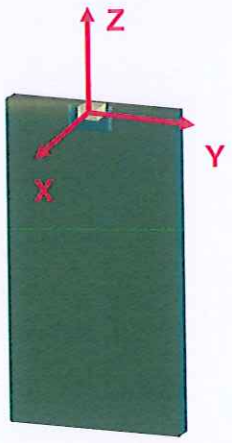


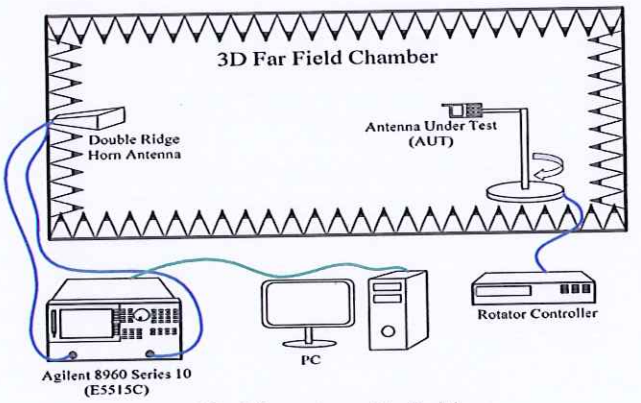
Return Loss & Radiation



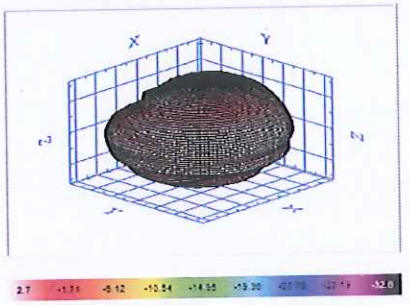
3D Radiation

3D Gain Pattern (2450 MHz)

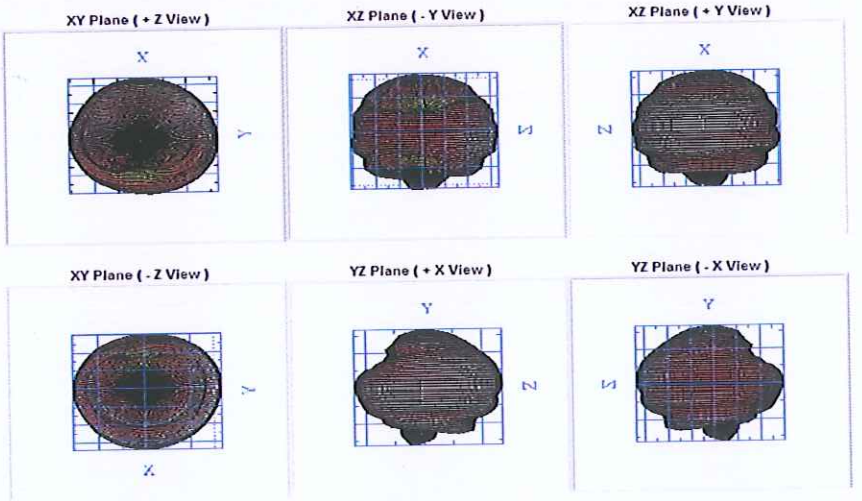




3D Chamber Definition



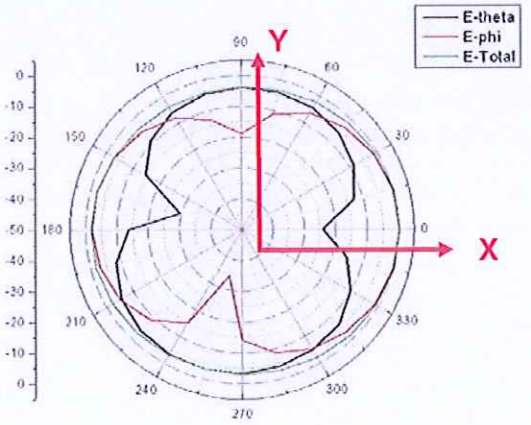
Frequency (MHz)	TRP (dBm)	Efficiency (%)
2450.00	-1.38	72.7
Peak EIRP (dBm)	Max. Power (dBm)	Directivity (dBi)
2.7	2.7	4.09
NHPRP +/- 45 (dBm)	Min. Power (dBm)	Average Gain (dB)
-2.41	-32.6	-1.38
NHPRP +/- 30 (dBm)	Avg. Power (dBm)	Upper Hem. (dBm)
-3.45	-1.13	-3.84
E-Theta Peak Gain (dBi)	Max. / Min. Ratio (dB)	Lower Hem. (dBm)
1.85	35.3	-5.02
E-Phi Peak Gain (dBi)	Max. / Avg. Ratio (dB)	Upper Hem. (%)
2.23	3.83	41.26
E-Total Peak Gain (dBi)	Min. / Avg. Ratio (dB)	Lower Hem. (%)
2.7	-31.47	31.45



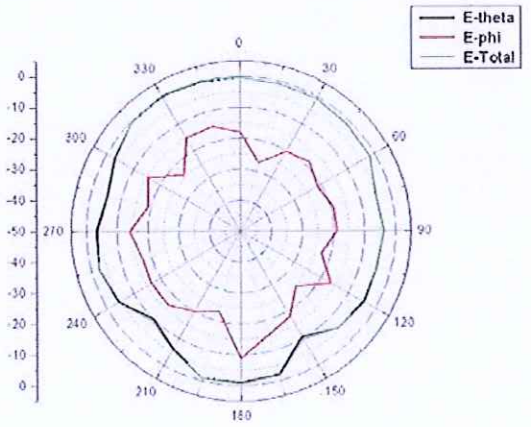
2D Radiation

◎ 2D Gain Pattern (2442 MHz)

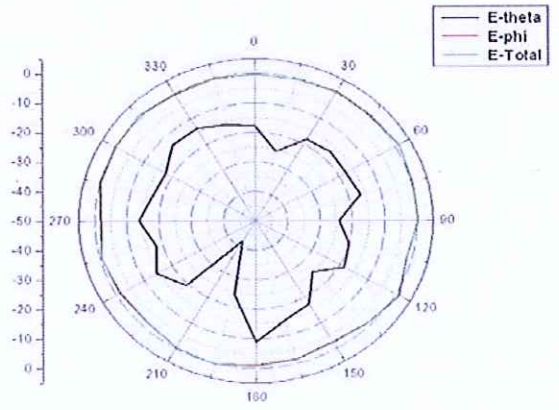
X-Y Plane



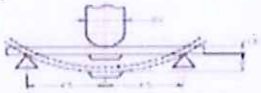
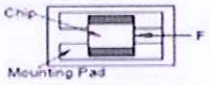
Y-Z Plane



X-Z Plane



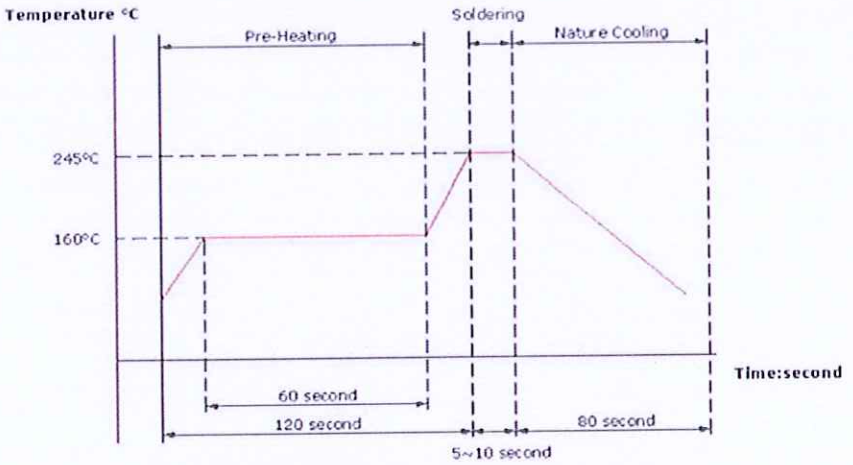
Rellability Of Ferrite Multllayer Chip Bead

No	Item	Specification	Test Method
1-1-1	Board Flex	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 60 sec 
1-1-2	Resistance to Soldenring Heat	Meet the electrical Specification after test	Refer to MIL- STD-202 Method 210 Pre-heating:150-200℃ ,60-100 sec Above 217℃,60-150 secs Peak Temperature: 260±5℃ ,20-40 sec Cycles: 2 times
1-1-3	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Refer to J-STD-002 Pre-heating:150℃ , 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃ ,(Pb-Free) Immersion Time: 4±1sec
1-1-4	Terminal Strength Test	The chip must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Force 2N for 60± 1 seconds for 0603 series Force 5N for 60± 1 seconds for 1005 series Force 10N for 60± 1 seconds for 1608 series Force 1.8Kg for 60± 1 seconds for other series 
1-1-5	Vibration Test	Meet the electrical Specification after test	Refer to MIL-STD-202 Method 204 Vbration waveform: Sine waveform Vbration frequency: 10Hz~2000Hz Vbration acceleration:5g 10Hz-20Hz and back to 10Hz should be in 20 minutes Duration of test:12cycles each of 3 orientations 20 minutes for each cycle, 12 hr total Vibration axes:X, Y, & Z
1-1-6	Resistance to Solvent	There must be no change in appearance or abliteration of marking	Refer to MIL-STD-202 Method 215 Inductors must withstand 6 mimutes of alcohol or water

Rellability Of Ferrite Multllayer Chip Bead

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Meet the electrical Specification afer test	Refer to JESD Method JA-104 Total cycles: 1000 cycles 30 minutes exposure to -40℃ 30 minutes exposure to 125℃ 1 min maximum transition between temperatures Measured after exposure in the room condition for 24hrs
1-2-2	Biased Humidity Resistance		Refer to MIL-STD-202 Method 103 Temperature: 85± 2℃ Relative Humidity : 85%/ Time:1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Exposure (Storage)		Refer to MIL-STD-202 Method 108 Temperature: 125± 3℃ /Relative Humidity: 0% Time:1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Exposure (Storage)	Meet the electrical Specification afer test	Refer to MIL-STD-202 Method 108 Temperature: -40± 3℃ /Relative Humidity: 0% Applied Current: Rated Current Time:1000hrs Measured after exposure in the room condition for 24hrs

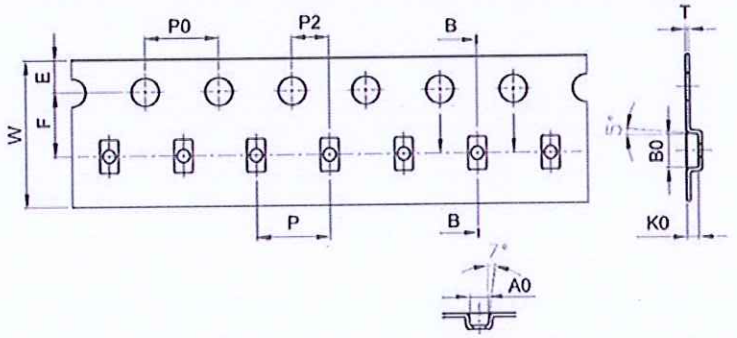
Slodering Conditions



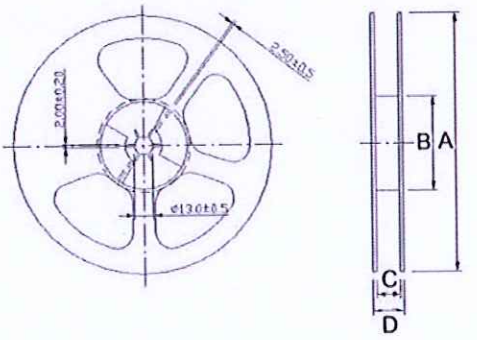
Lead Free Common Mode Fliter IR ReflowTemperature Profile

Packaging Specifications

Tape Dimensions



Reel Dimensions



Dimensions in mm

TYPE	Tape Dimensions										Reel Dimensions				Quantity
	A0	B0	T	E	W	P	P0	P2	F	K0	A	B	C	D	PCS / REEL
HCA2012B2450D08S	1.65	2.4	0.75	1.75	8	4	4	2	3.5	0.73	178	60	9.0	14.4	4000